

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
20 March 2025 (20.03.2025)



(10) International Publication Number
WO 2025/058881 A1

(51) International Patent Classification:

H01L 27/15 (2006.01) H01L 33/50 (2010.01)
H01L 25/075 (2006.01) H01L 33/36 (2010.01)
H01L 25/16 (2006.01) H01L 33/62 (2010.01)

(21) International Application Number:

PCT/US2024/045023

(22) International Filing Date:

03 September 2024 (03.09.2024)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/538,689 15 September 2023 (15.09.2023) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,

(54) Title: TEMPORARY UNDERFILL-BASED SELECTIVE MASS TRANSFER FOR M LED FABRICATION

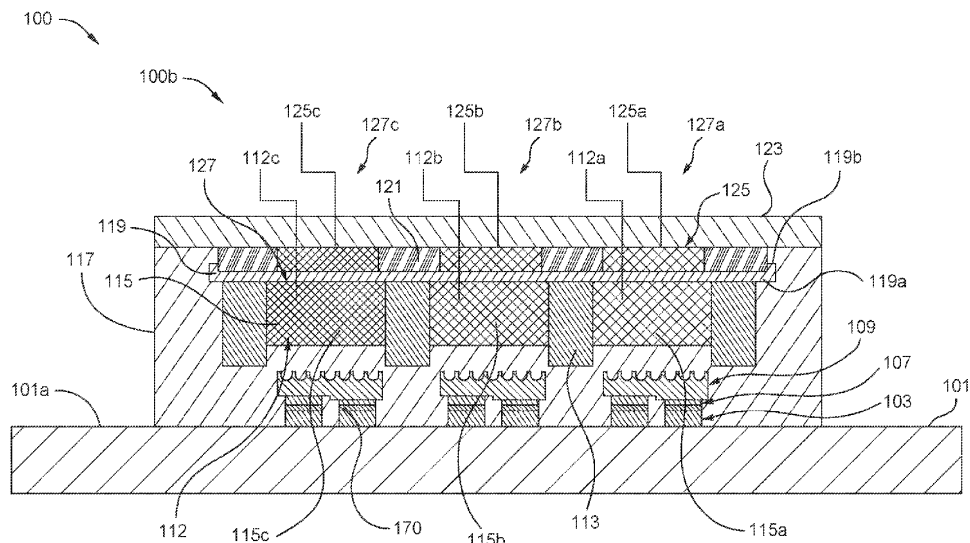


FIG. 1B

(57) Abstract: Embodiments of the present disclosure generally relate to LED pixels and methods of fabricating LED pixels. A device, includes micro-LEDs, micro-LED isolation structures, a transparent material, and an isolation substrate. The micro-LEDs are disposed over a backplane. Each micro-LED is coupled to at least one backplane electrode of the backplane. The micro-LED isolation structures are disposed over the backplane. Each micro-LED isolation structure is disposed between the at least one backplane electrode of adjacent micro-LEDs. The transparent material is disposed over the backplane between backplane electrodes, between the micro-LEDs, and over an emitting surface of each of the micro-LEDs. The isolation substrate has subpixel isolation (SI) structures disposed therein. The SI structures define wells of subpixels. The subpixels have a color conversion material disposed in wells and on the isolation substrate. The transparent material is between the color conversion materials.

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NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))
